

1.0 INTRODUCTION

This drawing describes the requirements for procuring the unpackaged integrated circuit die used in the manufacture of P/N MCC12040, a Phase-Frequency Detector. All changes and/or substitutions to the procured parts are subject to prior approval by Interpoint. This specification is to be used with GEN-008.

2.0 APPLICABLE DOCUMENTS

GEN-008 Integrated Circuit Dice

3.0 REQUIREMENTS

3.1 Mechanical/Physical Characteristics

Each die shall be configured per Figure 1 and Figure 2 or 3.

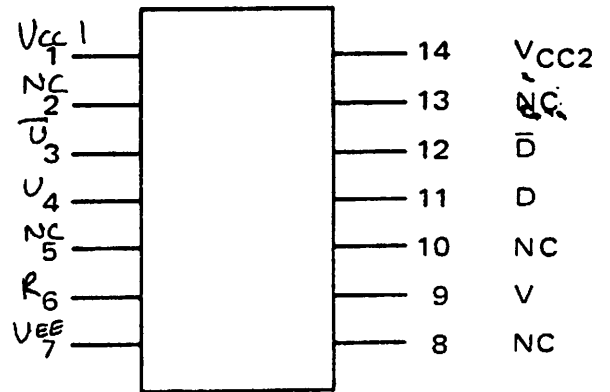
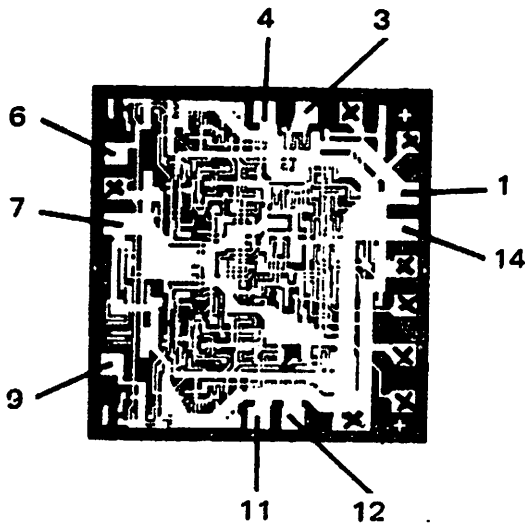


FIGURE 1
ELECTRICAL CONNECTION

- NOTES: 1. Mfr. Motorola
 2. Die size .061 x .063 ± .005
 3. Metallization - Topside: Al; Backside (Vee): Au or Si

FIGURE 2 - DIE CONFIGURATION